

Product Change Notification - JAON-06LEME647

Date:

14 Feb 2019

Product Category:

32-bit Microcontrollers

Affected CPNs:



Notification subject:

CCB 3497 Final Notice: Qualification of MMT as an additional assembly site for selected Atmel products of 58.85K wafer technology available in 100L TQFP (14x14x1.0mm) package.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected Atmel products of 58.85K wafer technology available in 100L TQFP (14x14x1.0mm) package.

Pre Change:

Assembled at ANAP using AuPd or PdCu wire, 3230 die attach, G700 mold compound and C194 leadframe material or assembled at ASE using PdCu or CuPdAu wire, CRM-1076WA die attach, EME-G631H mold compound and C7025 leadframe material.

Post Change:

Assembled at ANAP using AuPd or PdCu wire, 3230 die attach, G700 mold compound and C194 leadframe material or assembled at ASE using PdCu or CuPdAu wire, CRM-1076WA die attach, EME-G631H mold compound and C7025 leadframe material or assembled at MMT using Au wire, 3280 die attach, G700 mold compound and C7025 leadframe material.

Pre and Post Change Summary:

Pre and Post Change Summary:												
		Pre C	hange		Post Change							
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)		ASE Inc. Taiwan (ASE)		Amkor Technology Philippine (P1/P2), INC. (ANAP)		ASE Inc	Microchi p Technol ogy Thailand Branch (MMT)				
Wire material	AuPd	PdCu	PdCu	CuPdA u	AuPd	PdCu	PdCu	CuPdAu	Au			
Die attach material	3230		CRM-1076WA		3230		CRM-1076WA		3280			
Molding compound material	G700		EME-G631H		G700		EME-G631H		G700			
Lead frame	C194		C7025		C194		C7025		C7025			



material					
MSL	MSL 3				
Classification					

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying MMT as an additional new assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 8, 2019 (date code: 1910)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and

post change parts.

Time Table Summary:

-	August 2018					February 2019			March 2019					
Workweek	31	32	33	34	35	^	06	07	80	09	10	11	12	13
Initial PCN Issue Date		X												
Qual Report Availability								X						
Final PCN Issue Date								X						
Estimated Implementation											_			
Date											^			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

August 8, 2018: Issued initial notification.

February 14, 2019: Issued final notification. Attached the qualification report. Provided estimated first ship date on March 8, 2019. Updated the pre and post change summary table MSL classification for MMT site from MSL 1 and 2 to MSL 3.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN JAON-06LEME647 Qual Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

JAON-06LEME647 - CCB 3497 Final Notice: Qualification of MMT as an additional assembly site for selected Atmel products of 58.85K wafer technology available in 100L TQFP (14x14x1.0mm) package.

Affected Catalog Part Numbers (CPN)

AT32UC3A1128-AUR

AT32UC3A1128-AUT

AT32UC3A1256-AUR

AT32UC3A1256-AUT

AT32UC3A1512-AUR

AT32UC3A1512-AUT

AT32UC3C1128C-AUR

AT32UC3C1128C-AUT

AT32UC3C1256C-AUR

AT32UC3C1256C-AURA0

AT32UC3C1256C-AUT

AT32UC3C1512C-AUR

AT32UC3C1512C-AUT

AT32UC3C164C-AUR

AT32UC3C164C-AUT

ATSAM4LC2CA-AU

ATSAM4LC2CA-AUR

ATSAM4LC4CA-AU

ATSAM4LC4CA-AUR

ATSAM4LC8CA-AU

ATSAM4LC8CA-AUR

ATSAM4LS2CA-AU

ATSAM4LS2CA-AUR

ATSAM4LS4CA-AU

ATSAM4LS4CA-AUR

ATSAM4LS8CA-AU

ATSAM4LS8CA-AUR